FORM PTO-1449 (Modified)

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT(S)' INFORMATION DISCLOSURE STATEMENT

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ATTY. DOCKET NO.	SERIAL NO.
25916-0162 (6136/53804)	09/997,589
APPLICANTS Massingill et al.	
FILING DATE November 29, 2001	**GROUP ART UNIT** 1752

U.S. PATENT DOCUMENTS

EX'R INITIAL	*REF. #	PATENT NO.	DATE	NAME	U.S. CLASS/ SUBCLASS	FILING DATE if appropriate)
LT	A1	3,655,540	4/1972	Irvin	204/143 GE	6/1970
	*A2	3,791,858	2/1974	McPherson et al.	117/201	
	A3	3,867,272	2/1975	Rust et al.	204/194	1/1973
	*A4	3,976,524	8/1976	Feng	156/8	
	A5	4,045,312	8/1977	Satoshi	204/129.65	11/1975
	*A6	4,181,755	1/1980	Liu et al.	430/314	
	A7	4,248,683	2/1981	Shaw	204/129.3	4/1980
	*A8	4,614,021	9/1986	Hulseweh	29/590	
	A9	4,729,970	3/1988	Nath et al.	437/225	9/1986
	A10	4,749,454	6/1988	Arya et al.	204/129.3	11/1986
	A11	4,782,028	11/1988	Farrier et al.	437/3	8/1987
	*A12	4,908,940	3/1990	Amano et al.	29/852	
	*A13	4,915,983	4/1990	Lake et al.	427/98	
	*A14	4,921,777	5/1990	Fraenkel et al.	430/314	
	*A15	4,980,034	12/1990	Volfson et al.	437/195	
	A16	4,984,358	1/1991	Nelson	29/830	6/1990
	*A17	5,063,175	11/1991	Broadbent	437/192	
	*A18	5,071,518	12/1991	Pan	205/122	
	*A19	5,091,289	2/1992	Cronin et al.	430/312	
	*A20	5,097,393	3/1992	Nelson et al.	361/386	
	*A21	5,106,461	4/1992	Volfson et al.	205/125	
	*A22	5,118,385	6/1992	Kumar	156/644	
	*A23	5,137,597	8/1992	Curry, II et al.	156/636	
	*A24	5,162,260	11/1992	Leibovitz	427/195	
	A25	5,202,018	4/1993	Horányl et al.	204/129.2	7/1991
	*A26	5,283,081	2/1994	Kata et al.	427/96	
	*A27	5,287,619	2/1994	Smith et al.	29/852	
	*A28	5,316,974	5/1994	Crank	437/190	
	*A29	5,337,466	8/1994	Ishida	29/830	
	*A30	5,464,653	11/1995	Chantraine et al.	427/96	
	*A31	5,512,514	4/1996	Lee	437/195	
	A32	5,543,585	8/1996	Booth et al.	174/261	2/1994
	A33	5,591,678	1/1997	Bendik et al.	437/208	6/1995
	*A34	5,654,237	8/1997	Suguro et al.	438/624	
	A35	5,656,548	8/1997	Zavracky et al.	438/23	9/1995
	A36	5,656,552	8/1997	Hudak et al.	438/15	6/1996
	*A37	5,699,613	12/1997	Chong et al.	29/852	
	A38	5,716,881	2/1998	Liang et al.	438/238	3/1996
	A39	5,734,555	3/1998	McMahon	361/704	3/1994
	A40	5,770,487	6/1998	Mass et al.	438/164	4/1996
	A41	5,784,261	7/1998	Pedder	361/767	1/1996
LT	*A42	5,784,782	7/1998	Boyko et al.	29/848	

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U.S. PATENT DOCUMENTS CONT'D

EX'R INITIAL	*REF. #	PATENT NO.	DATE	NAME	U.S. CLASS/ SUBCLASS	FILING DATE if appropriate)
LT	A43	5,807,783	9/1998	Gaul et al.	438/406	10/1996
	A44	5,811,879	9/1998	Akram	257/723	11/1997
	*A45	5,830,533	11/1998	Lin et al.	427/272	
	*A46	5,834,845	11/1998	Stolmeijer	257/752	
	A47	5,838,545	11/1998	Clocher et al.	361/719	10/1996
	A48	5,843,806	12/1998	Tsai	438/107	11/1997
	*A49	5,843,839	12/1998	Ng	438/637	
	A50	5,851,845	12/1998	Wood et al.	438/15	12/1995
	A51	5,856,937	1/1999	Chu et al.	365/51	6/1997
	A52	5,859,397	1/1999	Ichinose et al.	204/157.15	5/1997
	A53	5,863,412	1/1999	Ichinose et al.	205/652	10/1996
	A54	5,863,829	1/1999	Nakayoshi et al.	438/459	11/1996
	A55	5,866,441	2/1999	Pace	438/108	12/1996
	A56	5,872,025	2/1999	Cronin et al.	438/109	3/1997
	A57	5,872,700	2/1999	Collander	361/760	7/1997
	A58	5,877,034	3/1999	Ramm et al.	438/15	9/1995
	*A59	5,891,606	4/1999	Brown	430/312	
	*A60	5,891,799	4/1999	Tsui	438/624	
	*A61	5,916,453	6/1999	Beilin et al.	216/38	
LT	*A62	6,013,417	1/2000	Sebesta et al.	430/312	

FOREIGN PATENT DOCUMENTS

EX'R INITIAL	*REF. #	PATENT NO.	DATE	COUNTRY	CLASS/SUBCLASS	TRANSLATION	
						yes	no
LT	*B1	56-116697	9/1981	JAPAN	3/46	X	
LT	*B2	63-244796	10/12/88	JAPAN	3/46	X	

OTHER ART

EX'R INITIAL	*REF. #	INCLUDE AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
LT	*C1	Pan et al., "A Planar Approach to High Density Copper-Polymide Interconnect Fabrication," pp. 174-189, Proceeding of the Technical Conference - 8th Int'l Electronics Packaging Conference (1988).
LT	*C2	Iwasaki et al., "A Pillar-Shaped Via Structure in a Cu-Polymide Multilayer Substrate," pp. 127-131, Proceedings of the 1989 Japan International Electronic Manufacturing Technology Symposium.

EXAMINER	DATE CONSIDERED
Luan Thai	12/08/03

EXAMINER: **Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance *and* not considered. Include copy of this form with next communication to Applicant(s).**